

## 100V N-Channel Enhancement Mode MOSFET

Voltage	100 V	R <sub>DSON</sub>	4.4 mΩ
Current	122 A	Q <sub>G</sub> (TYP)	40.5 nC

### Feature

- R<sub>DSON</sub> < 4.4 mΩ at V<sub>GS</sub> = 10 V, I<sub>D</sub> = 50 A
- R<sub>DSON</sub> < 6.5 mΩ at V<sub>GS</sub> = 6 V, I<sub>D</sub> = 25 A
- High switching speed
- Low reverse transfer capacitance
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

### Mechanical Data

- Case: DFN5060-8L Package
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 0.08 grams

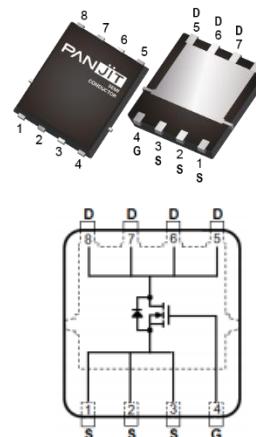
### Application

- SR solutions of PD Charger, Brick Power, 48V DC/DC converter

### Absolute Maximum Ratings (T<sub>A</sub> = 25 °C unless otherwise specified)

PARAMETER	SYMBOL	LIMIT	UNITS
Drain-Source Voltage	V <sub>DS</sub>	100	V
Gate-Source Voltage	V <sub>GS</sub>	±20	
Continuous Drain Current (Note 3)	I <sub>D</sub>	122	A
T <sub>C</sub> =25 °C		77	
T <sub>C</sub> =100 °C			
Pulsed Drain Current	I <sub>DM</sub>	488	A
T <sub>C</sub> =25 °C			
Single Pulse Avalanche Current (Note 5)	I <sub>AS</sub>	50	A
Single Pulse Avalanche Energy (Note 5)	E <sub>AS</sub>	318	mJ
Power Dissipation	P <sub>D</sub>	125	W
T <sub>C</sub> =25 °C		50	
T <sub>C</sub> =100 °C			
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55~150	°C

DFN5060-8L



Top side view

### Thermal Characteristics

PARAMETER	SYMBOL	MAXIMUM	UNITS
Thermal Resistance	R <sub>θJC</sub>	1.0	°C/W
Junction-to-Case (Bottom)			
Junction-to-Ambient (Note 4)	R <sub>θJA</sub>	50	°C/W

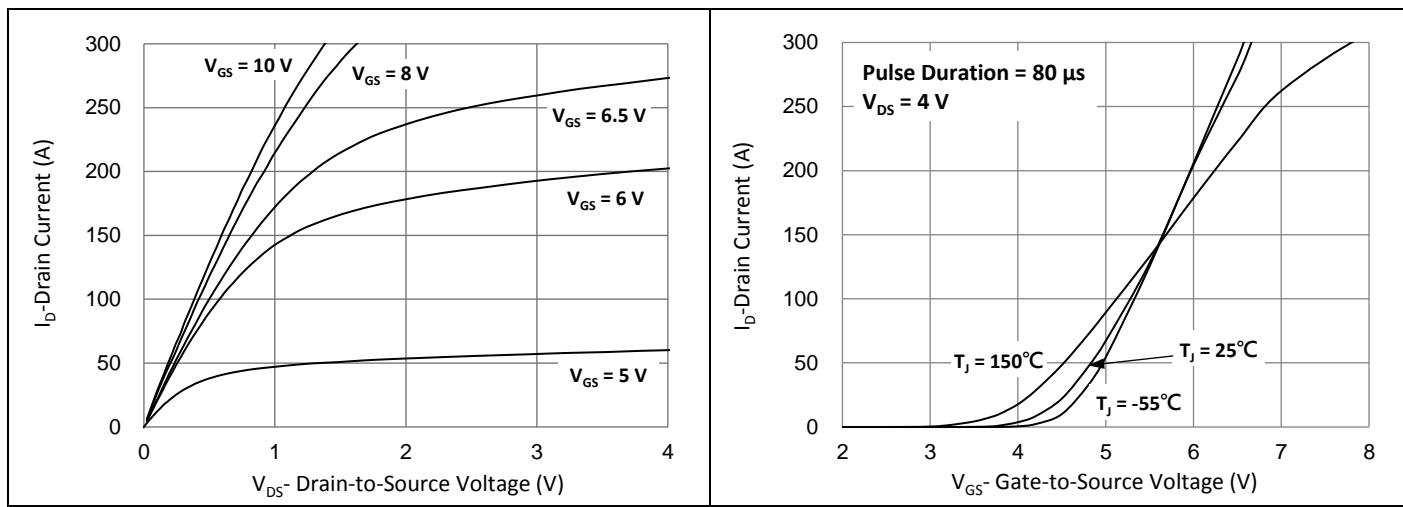
**Electrical Characteristics ( $T_A = 25^\circ\text{C}$  unless otherwise specified)**

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS
<b>Static</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$\text{V}_{\text{GS}}=0 \text{ V}, \text{I}_D=250 \mu\text{A}$	100	-	-	V
Gate Threshold Voltage	$\text{V}_{\text{GS(th)}}$	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=270 \mu\text{A}$	1.8	2.8	3.8	
Drain-Source On-State Resistance (Note 1)	$\text{R}_{\text{DS(on)}}$	$\text{V}_{\text{GS}}=10 \text{ V}, \text{I}_D=50 \text{ A}$	-	3.8	4.4	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=6 \text{ V}, \text{I}_D=25 \text{ A}$	-	5.0	6.5	
Zero Gate Voltage Drain Current	$\text{I}_{\text{DSS}}$	$\text{V}_{\text{DS}}=100 \text{ V}, \text{V}_{\text{GS}}=0 \text{ V}$	-	-	1	$\mu\text{A}$
Gate-Source Leakage Current	$\text{I}_{\text{GSS}}$	$\text{V}_{\text{GS}}=\pm 20 \text{ V}, \text{V}_{\text{DS}}=0 \text{ V}$	-	-	$\pm 100$	$\text{nA}$
Transfer characteristics (Note 1)	$\text{g}_{\text{fs}}$	$\text{V}_{\text{DS}}=10 \text{ V}, \text{I}_D=50 \text{ A}$	-	105	-	S
<b>Dynamic (Note 6)</b>						
Total Gate Charge	$\text{Q}_g$	$\text{V}_{\text{DS}}=50 \text{ V}, \text{I}_D=50 \text{ A}, \text{V}_{\text{GS}}=10 \text{ V}$	-	40.5	53	nC
Gate-Source Charge	$\text{Q}_{\text{gs}}$		-	15	-	
Gate-Drain Charge	$\text{Q}_{\text{gd}}$		-	6	-	
Gate Plateau Voltage	$\text{V}_{\text{plateau}}$		-	5	-	V
Input Capacitance	$\text{C}_{\text{iss}}$	$\text{V}_{\text{DS}}=50 \text{ V}, \text{V}_{\text{GS}}=0 \text{ V}, \text{f}=250 \text{ kHz}$	-	3010	3910	pF
Output Capacitance	$\text{C}_{\text{oss}}$		-	1080	1400	
Reverse Transfer Capacitance	$\text{C}_{\text{rss}}$		-	14	-	
Output Charge	$\text{Q}_{\text{oss}}$	$\text{V}_{\text{DS}}=50 \text{ V}, \text{V}_{\text{GS}}=0 \text{ V}$	-	85	110	nC
Turn-On Delay Time	$\text{t}_{\text{d(on)}}$	$\text{V}_{\text{DD}}=50 \text{ V}, \text{I}_D=50 \text{ A}, \text{V}_{\text{GS}}=10 \text{ V}, \text{R}_G=6.0 \Omega$ (Note 2)	-	11	-	ns
Rise Time	$\text{t}_r$		-	6	-	
Turn-Off Delay Time	$\text{t}_{\text{d(off)}}$		-	22	-	
Fall Time	$\text{t}_f$		-	8	-	
Gate Resistance	$\text{R}_g$	$f=1.0 \text{ MHz}$	-	0.8	1.6	$\Omega$
<b>Drain-Source Diode</b>						
Diode Forward Voltage	$\text{V}_{\text{SD}}$	$\text{I}_s=50 \text{ A}, \text{V}_{\text{GS}}=0 \text{ V}$	-	0.9	1.2	V
Reverse Recovery Charge	$\text{Q}_{\text{rr}}$	$\text{I}_F=50 \text{ A}, \text{V}_{\text{DD}}=50 \text{ V}$ $d\text{i}/dt=100 \text{ A}/\mu\text{s}$	-	85	-	nC
Reverse Recovery Time	$\text{T}_{\text{rr}}$		-	56	-	ns

NOTES :

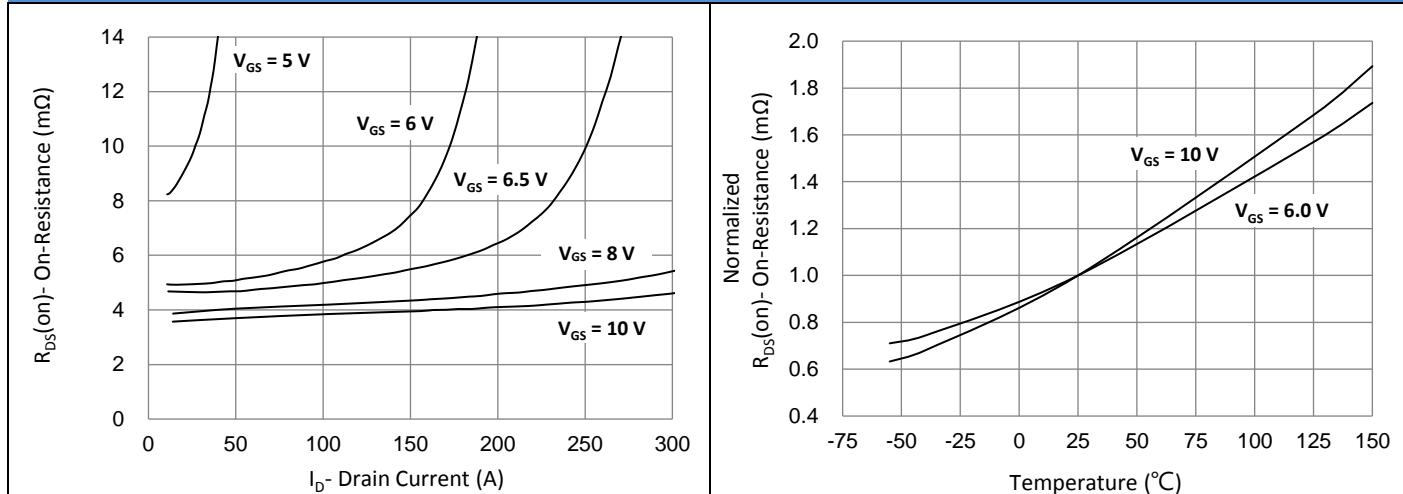
1. Pulse width  $\leq 300 \mu\text{s}$ , Duty cycle  $\leq 2\%$
2. Essentially independent of operating temperature typical characteristics.
3. The maximum drain current calculated by maximum junction temperature and thermal impedance. It can be varied by application and environment.
4.  $\text{R}_{\theta\text{JA}}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch<sup>2</sup> with 2oz.square pad of copper.
5.  $\text{E}_{\text{AS}}$  is calculated based on the condition of  $L = 1.0 \text{ mH}$ ,  $\text{I}_{\text{AS}} = 25.2 \text{ A}$ ,  $\text{V}_{\text{DD}} = 50 \text{ V}$ ,  $\text{V}_{\text{GS}} = 10 \text{ V}$ . 100% test at  $L = 0.1 \text{ mH}$ ,  $\text{I}_{\text{AS}} = 50 \text{ A}$  in production.
6. Guaranteed by design, not subject to production testing.

**TYPICAL CHARACTERISTIC CURVES**



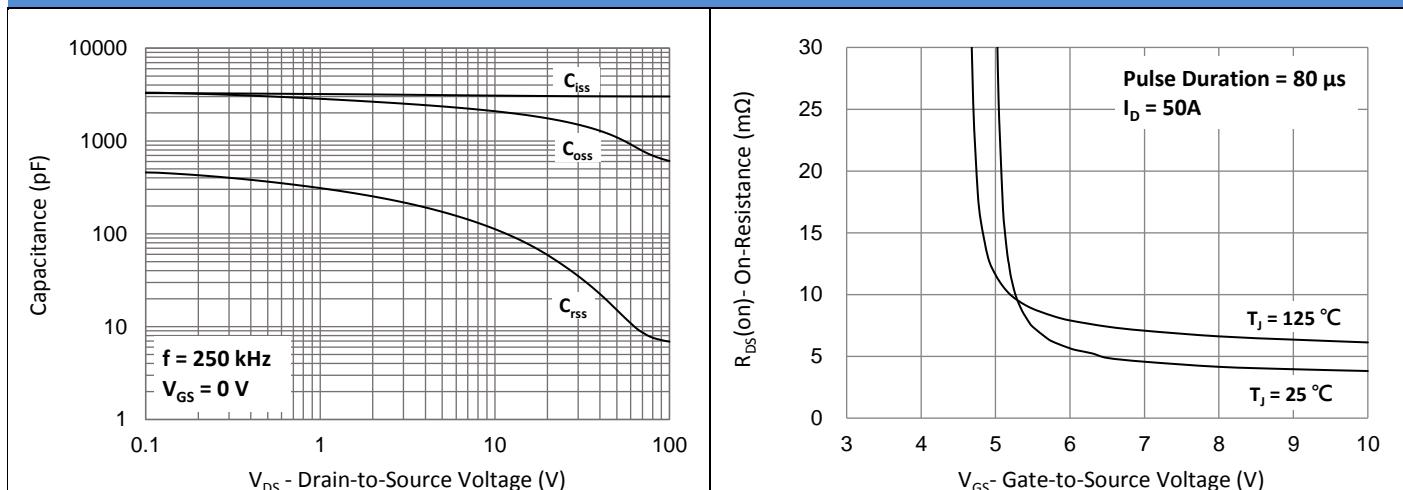
**Fig.1 Output Characteristics**

**Fig.2 Transfer Characteristics**



**Fig.3 On-Resistance vs. Drain Current**

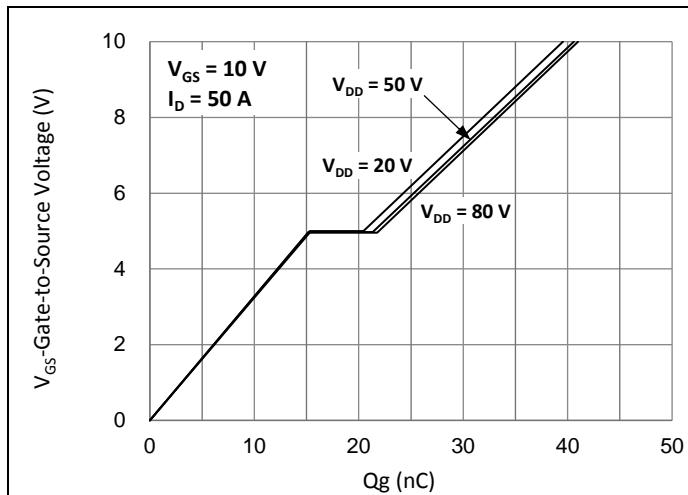
**Fig.4 On-Resistance vs. Junction temperature**



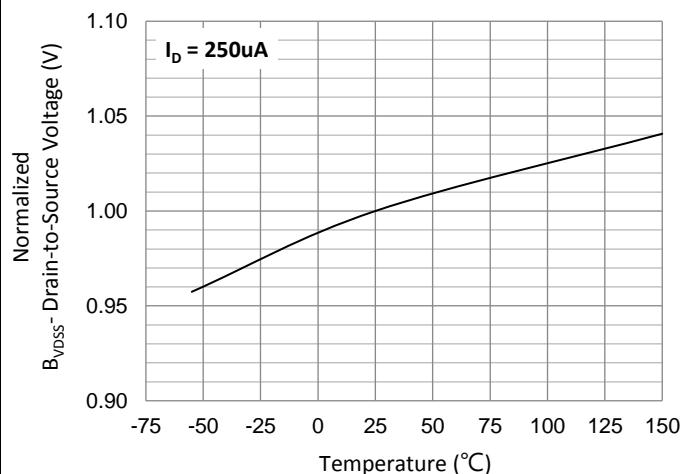
**Fig.5 Capacitance vs. Drain-Source Voltage**

**Fig.6 On-Resistance vs. Gate-Source Voltage**

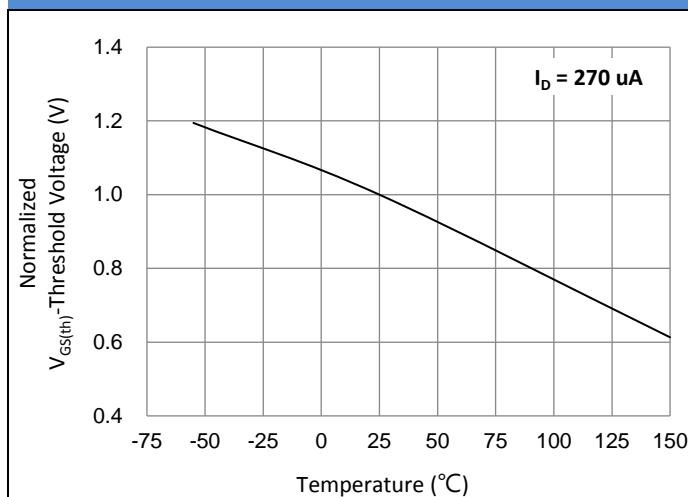
**TYPICAL CHARACTERISTIC CURVES**



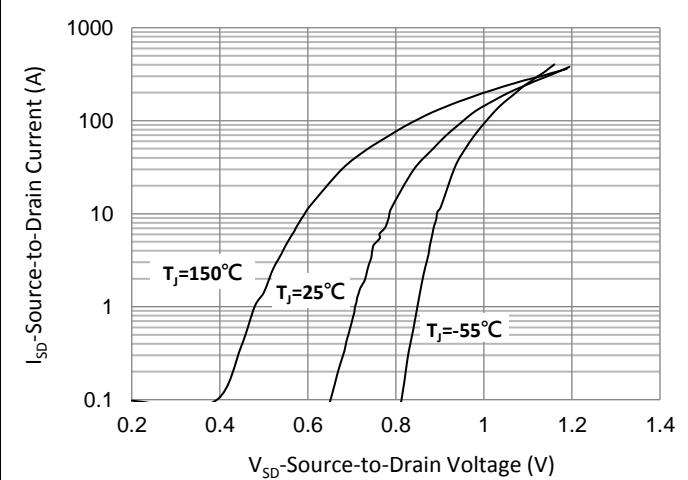
**Fig.7 Gate-Charge Characteristics**



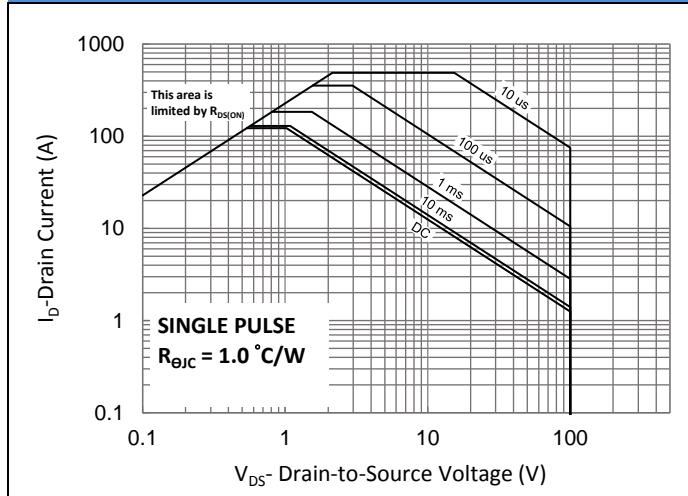
**Fig.8 Breakdown Voltage Variation vs. Temperature**



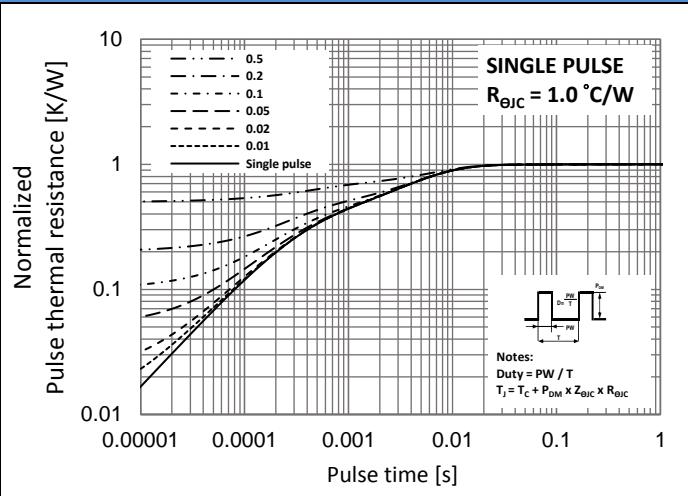
**Fig.9 Threshold Voltage Variation with Temperature**



**Fig.10 Source-Drain Diode Forward Voltage**

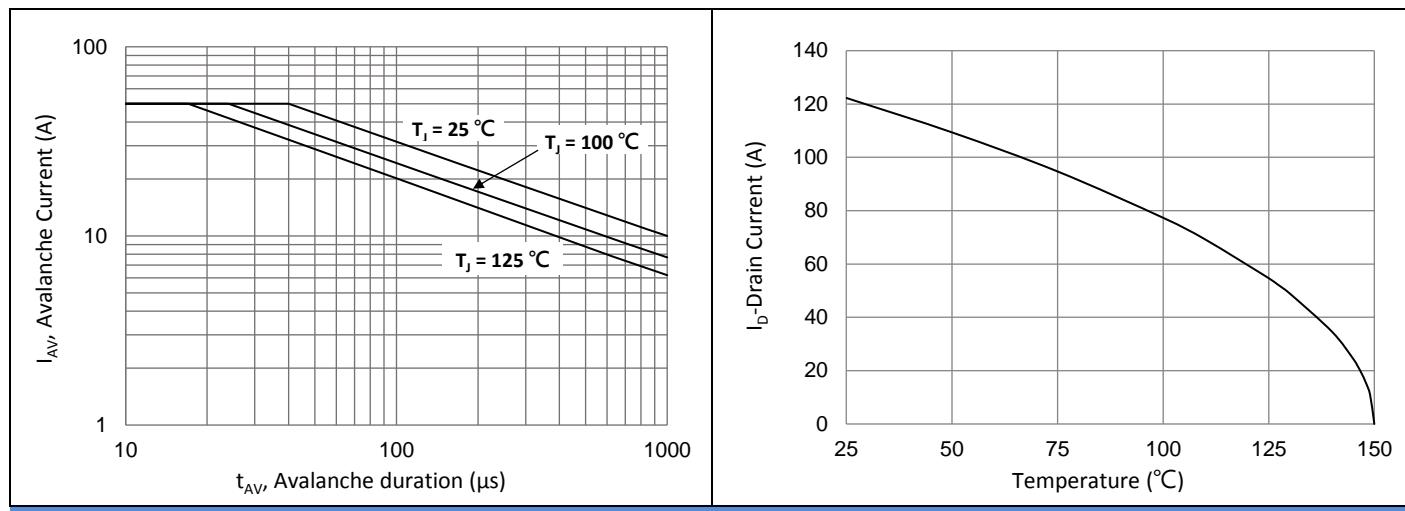


**Fig.11 Maximum Safe Operating Area**



**Fig.12 Normalized Transient Thermal Impedance**

**TYPICAL CHARACTERISTIC CURVES**



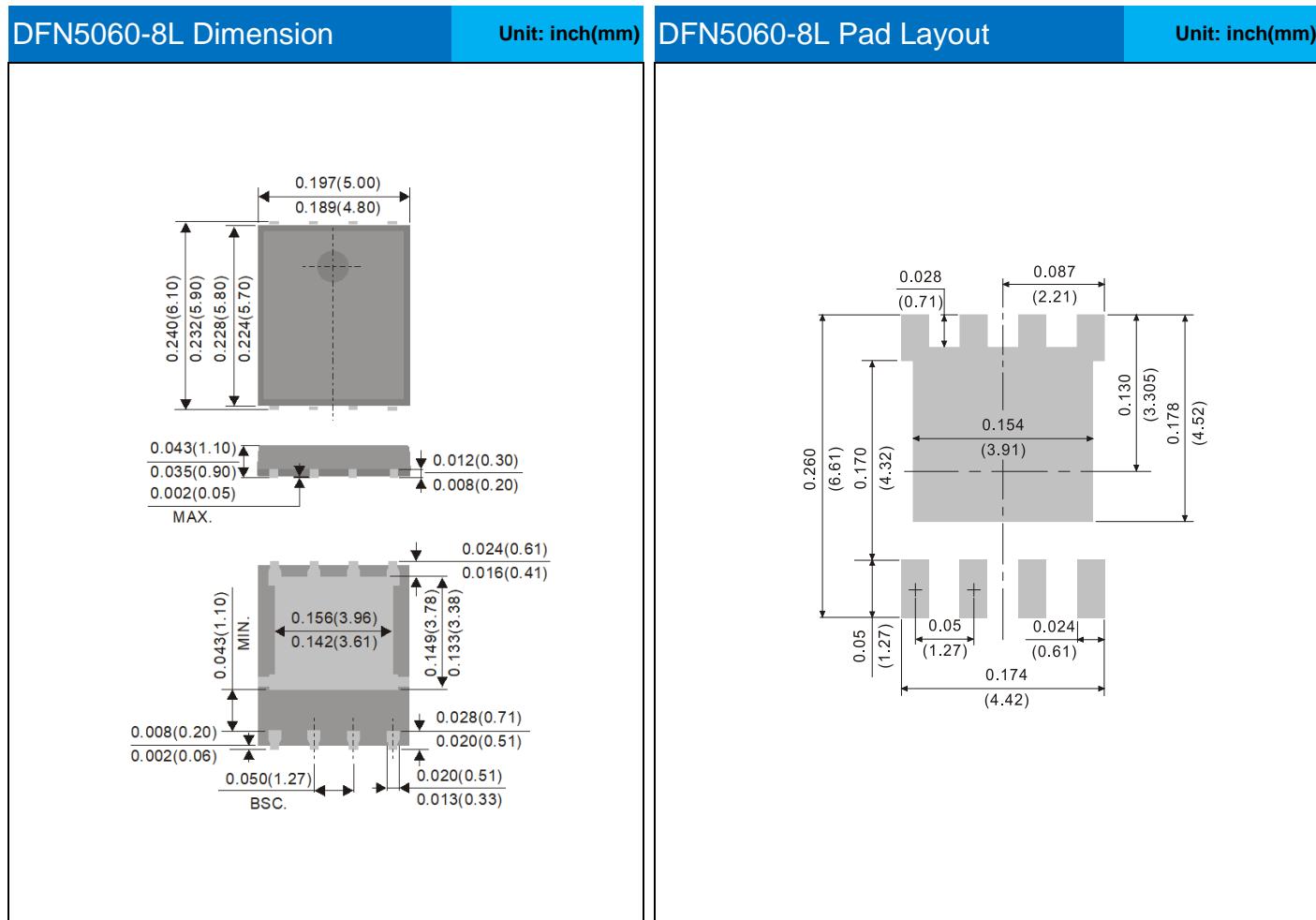
**Fig.13 Avalanche Characteristics**

**Fig.14 Drain Current vs. Case Temperature**

## Product and Packing Information

Part No.	Package Type	Packing Type	Marking
PSMQC040N10NS2	DFN5060-8L	3000pcs / 13" reel	040N10NS

## Packaging Information & Mounting Pad Layout



## Marking Diagram

PJ  
040N10NS  
YWLL x

**Y** = Year Code  
**W** = Week Code (A~Z)  
**LL** = Lot Code (00~99)  
**x** = Production Line Code

## Disclaimer

- Reproducing and modifying information of the document is prohibited without permission from Panjit International Inc..
- Panjit International Inc. reserves the rights to make changes of the content herein the document anytime without notification. Please refer to our website for the latest document.
- Panjit International Inc. disclaims any and all liability arising out of the application or use of any product including damages incidentally and consequentially occurred.
- Panjit International Inc. does not assume any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.
- Applications shown on the herein document are examples of standard use and operation. Customers are responsible in comprehending the suitable use in particular applications. Panjit International Inc. makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.
- The products shown herein are not designed and authorized for equipments requiring high level of reliability or relating to human life and for any applications concerning life-saving or life-sustaining, such as medical instruments, transportation equipment, aerospace machinery et cetera. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Panjit International Inc. for any damages resulting from such improper use or sale.
- Since Panjit uses lot number as the tracking base, please provide the lot number for tracking when complaining.